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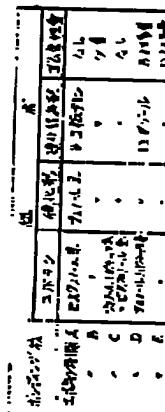
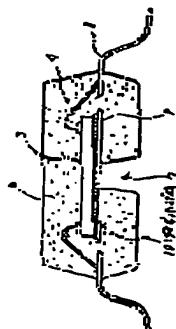
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(54) HIGH HEAT-RESISTANT RESIN-SEALING TYPE SEMICONDUCTOR DEVICE

(57) Abstract:
PURPOSE: To prevent a package from being deformed or cracked due to heating exceeding 200-C when packaging a substrate by using an organic macromolecular adhesive with a specific elasticity modulus of an adhesive-curing substance and a specific rate of moisture absorption under specific conditions.

CONSTITUTION: Five kinds of epoxy resins with different composition and a polyimide resin are used as a die-bonding material 10 for adhesion and resin-sealing is performed for production in die bonding of a semiconductor chip 3 on an island 2 of a lead frame, where elasticity modulus of an adhesive-curing agent exceeding 200-C is equal to or larger than 47109dyn/cm² and a rate of moisture absorption after leaving for 72 hours at 85-C/85% R.H. (relative humidity) is equal to 0.2% or smaller.



LEGAL STATUS

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